

SYSTEM AND METHOD FOR PEELING A SEMICONDUCTOR CHIP FROM A TAPE USING A MULTISTAGE EJECTOR

ABSTRACT

A system and method for peeling a semiconductor chip from a tape using a multistage ejector is disclosed. A housing in the multistage ejector houses a plural sets of tape removing contacts. A pick and place unit is moved slowly to have contact with the chip. A vacuum source is utilized for generating vacuum to suck the tape. Plural sets of contacts such as inner, middle and outer contacts are independently or together moved below the tape at various stages by utilizing their respective actuation mechanism. A controller can independently control the movements of each contact to effectively remove or loosen the tape from the chip. A pick and place unit can then pick up the chip easily without any damage to chip.

[FIG. 2]